



IPW

PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q78432

Hien Boon TAN, et al.

Appln. No.: 10/721,382

Group Art Unit: 2822

Confirmation No.: 6007

Examiner: David E. Graybill

Filed: November 25, 2003

For: HIGH DENSITY CHIP SCALE LEADFRAME PACKAGE AND METHOD OF
MANUFACTURING THE PACKAGE

RESPONSE TO RESTRICTION REQUIREMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In response to the Restriction Requirement, dated June 10, 2005, Applicant elects Group II, claims 21-26 for examination. This election is made without traverse.

Applicant reserves the right to file a Divisional Application directed to non-elected claims 1-20.

The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account.

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WASHINGTON OFFICE

23373

CUSTOMER NUMBER

Date: July 8, 2005

Respectfully submitted,

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